

512K X 32 BIT HIGH SPEED CMOS SRAM

Revision History AS7C351232-10BIN 90ball TFBGA PACKAGE

Revision	Details	Date
Rev 1.0	Initial Issue	Jan. 2017

Alliance Memory Inc. 511 Taylor Way, San Carlos, CA 94070 TEL: (650) 610-6800 FAX: (650) 620-9211 Alliance Memory Inc. reserves the right to change products or specification without notice



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FEATURES

- Fast access time : 10ns
- Low power consumption: Operating current : 125mA (TYP.) Standby current : 4mA (TYP.)
- Single 3.3V power supply
- All inputs and outputs TTL compatible
- Fully static operation
- Tri-state output
- Data byte control : B0# (DQ0 ~ DQ7) B1# (DQ8 ~ DQ15)
 - B2# (DQ16~DQ23)
 - B3# (DQ24~DQ31)
- Data retention voltage : 1.5V (MIN.)
- ROHS Compliant/Pb & Halogen free
- Package : 90-ball 8mm x 13mm TFBGA

PRODUCT FAMILY

GENERAL DESCRIPTION

The AS7C351232-10BIN is a 16M-bit high speed CMOS static random access memory organized as 512K words by 32 bits. It is fabricated using very high performance, high reliability CMOS technology. Its standby current is stable within the range of operating temperature.

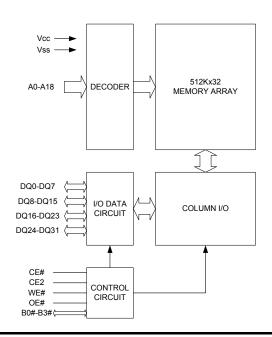
The AS7C351232-10BIN operates from a single power supply of 3.3V and all inputs and outputs are fully TTL compatible

Product	Operating	V _{cc} Range	Danga Speed	Power Dissipation		
Family	Temperature	VCC Range	Speed	Standby(IsB1,TYP.)	Operating(Icc,TYP.)	
AS7C351232-10BIN	-40 ~ 85℃	2.7 ~ 3.6V	10ns	4mA	125mA	

ORDERING INFORMATION

Package Type	Access Time (Speed/ns)	Temperature Range(°C)	Packing Type	Alliance Part Number
90-ball (8mm x 13mm)	10	-40°C~85°C	Tray	AS7C351232-10BIN
TFBGA	10		Tape Reel	AS7C351232-10BINTR

FUNCTIONAL BLOCK DIAGRAM



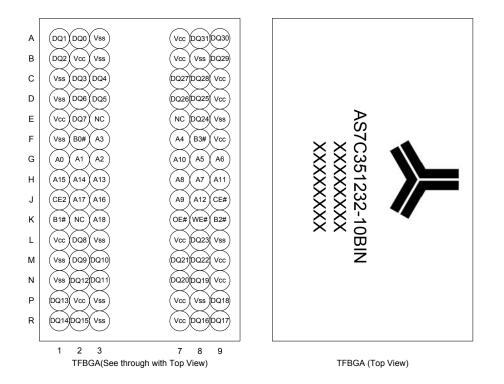
PIN DESCRIPTION

SYMBOL	DESCRIPTION
A0 - A18	Address Inputs
DQ0 - DQ31	Data Inputs/Outputs
CE#, CE2	Chip Enable Input
WE#	Write Enable Input
OE#	Output Enable Input
B0# - B3#	Byte Control
Vcc	Power Supply
Vss	Ground
NC	No Connection



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PIN CONFIGURATION





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ABSOLUTE MAXIMUM RATINGS*

PARAMETER	SYMBOL	RATING	UNIT
Voltage on V_{CC} relative to V_{SS}	V _{T1}	-0.5 to 4.6	V
Voltage on any other pin relative to Vss	V _{T2}	-0.5 to V _{CC} +0.5	V
Operating Temperature	T _A	-40 to 85(I grade)	°C
Storage Temperature	Тѕтс	-65 to 150	°C
Power Dissipation	PD	1	W
DC Output Current	Іоит	50	mA

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the absolute maximum rating conditions for extended period may affect device reliability.

TRUTH TABLE

MODE	CE# CE2 OE#				B1#	B0# B1#		I/O OPERATION				SUPPLY	
WODE	CL#	ULZ		**∟#	D0#	Ы#	DU#	DI#	DQ0-7	DQ8-15	DQ16-23	DQ24-31	CURRENT
Standby	Н	Х	Х	Х	Х	Х	Х	Х	High-Z	High-Z	High-Z	High-Z	I _{SB1}
Stanuby	Х	L	Х	Х	Х	Х	Х	Х	High-Z	High-Z	High-Z	High-Z	ISB1
Output Disable	L	Н	Н	Н	Х	Х	Х	Х	High-Z	High-Z	High-Z	High-Z	lcc
	L	Н	Х	Х	Н	Н	Н	Н	High-Z	High-Z	High-Z	High-Z	ICC
	L	Н	L	Н	L	Н	Н	Н	Dout	High-Z	High-Z	High-Z	
	L	Н	L	Н	Н	L	Н	Н	High-Z	Dout	High-Z	High-Z	
Read	L	Н	L	Н	Н	Н	L	Н	High-Z	High-Z	Dout	High-Z	lcc
	L	Н	L	Н	Н	Н	Н	L	High-Z	High-Z	High-Z	Dout	
	L	Н	L	Н	L	L	L	L	Dout	Dout	Dout	Dout	
	L	Η	Х	L	L	Η	Н	Η	Din	High-Z	High-Z	High-Z	
	L	Н	Х	L	Н	L	Н	Н	High-Z	DIN	High-Z	High-Z	
Write	L	Н	Х	L	Н	Н	L	Н	High-Z	High-Z	DIN	High-Z	lcc
	L	Н	Х	L	Н	Н	Н	L	High-Z	High-Z	High-Z	DIN	
	L	Н	Х	L	L	L	L	L	DIN	DIN	DIN	DIN	

Note: $H = V_{IH}$, $L = V_{IL}$, X = Don't care.



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DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYM.	TEST CONDITION	MIN.	TYP. *4	MAX.	UNIT	
Supply Voltage	Vcc			2.7	3.3	3.6	V
Input High Voltage	VIH*1			2.2	-	Vcc+0.3	V
Input Low Voltage	VIL*2			- 0.3	-	0.8	V
Input Leakage Current	lι	$V_{CC} \ge V_{IN} \ge V_{SS}$		- 1	-	1	μA
Output Leakage Current	Ilo	Vcc≧ Vouт≧ Vss, Output Disabled		- 1	-	1	μA
Output High Voltage	Vон	I _{ОН} = -4mA		2.4	-	-	V
Output Low Voltage	Vol	I _{OL} = 8mA		-	-	0.4	V
Average Operating Power supply Current	lcc	$\begin{array}{l} CE\# \leqq 0.2V \text{ and } CE2 \geqq \ V_{CC}\text{-}0.2V, \\ \text{other pins at } 0.2V \text{ or } V_{CC}\text{-}0.2V, \\ I_{VO} = 0mA; \ f=max. \end{array}$	-10	-	125	180	mA
Standby Power Supply Current	I _{SB1}	$\begin{array}{ll} CE\# \geqq & V_{\mathrm{CC}} \text{-} 0.2V;\\ \text{other pins at } 0.2V \text{ or } V_{\mathrm{CC}} \text{-} 0.2V. \end{array}$	•	-	4	40	mA

Notes:

1. $V_{IH}(MAX.) = V_{CC} + 2.0V$ for pulse width less than 6ns. 2. $V_{IL}(MIN.) = V_{SS} - 2.0V$ for pulse width less than 6ns.

3. Over/Undershoot specifications are characterized on engineering evaluation stage, not for mass production test.

4. Typical values are included for reference only and are not guaranteed or tested.

Typical valued are measured at V_{CC} = V_{CC}(TYP.) and T_A = 25° C

CAPACITANCE (T_A = 25°C, f = 1.0MHz)

PARAMETER	SYMBOL	MIN.	MAX.	UNIT
Input Capacitance	CIN	-	8	pF
Input/Output Capacitance	Cı/o	-	10	pF

Note : These parameters are guaranteed by device characterization, but not production tested.

AC TEST CONDITIONS

Speed	10 ns
Input Pulse Levels	0.2V to Vcc-0.2V
Input Rise and Fall Times	3ns
Input and Output Timing Reference Levels	Vcc/2
Output Load	CL = 30pF + 1TTL, Iон/IоL = -4mA/8mA



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AC ELECTRICAL CHARACTERISTICS

(1) READ CYCLE

PARAMETER	SYM.	AS7C351	232-10BIN	UNIT
FARAMETER	5 T WI.	MIN.	MAX.	UNIT
Read Cycle Time	t _{RC}	10	-	ns
Address Access Time	taa	-	10	ns
Chip Enable Access Time	tace	-	10	ns
Output Enable Access Time	toe	-	4.5	ns
Chip Enable to Output in Low-Z	tcLz*	2	-	ns
Output Enable to Output in Low-Z	tolz*	0	-	ns
Chip Disable to Output in High-Z	tснz*	-	4	ns
Output Disable to Output in High-Z	tонz*	-	4	ns
Output Hold from Address Change	toн	2	-	ns
Byte Control Access Time	tвA	-	4.5	ns
Byte Control to High-Z Output	tвнz*	-	4	ns
Byte Control to Low-Z Output	t _{BLZ} *	0	-	ns

(2) WRITE CYCLE

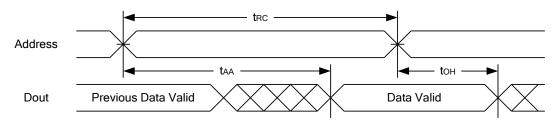
PARAMETER	SYM.	AS7C351		
PARAWETER	5111.	MIN.	MAX.	
Write Cycle Time	twc	10	-	ns
Address Valid to End of Write	taw	8	-	ns
Chip Enable to End of Write	tcw	8	-	ns
Address Set-up Time	tas	0	-	ns
Write Pulse Width	twp	8	-	ns
Write Recovery Time	twr	0	-	ns
Data to Write Time Overlap	tow	6	-	ns
Data Hold from End of Write Time	t _{DH}	0	-	ns
Output Active from End of Write	tow*	2	-	ns
Write to Output in High-Z	twнz*	-	4	ns
Byte Control Valid to End of Write	tвw	8	-	ns

*These parameters are guaranteed by device characterization, but not production tested.

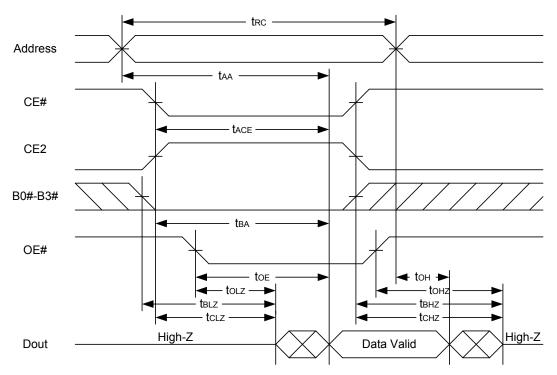


TIMING WAVEFORMS

READ CYCLE 1 (Address Controlled) (1,2)



READ CYCLE 2 (CE# and CE2 and OE# Controlled) (1,3,4,5)



Notes :

2.Device is continuously selected OE# = low, CE# = low, CE2 = high, and B0#, B1#, B2# or B3# = low.

3.Address must be valid prior to or coincident with CE# = low, CE2 = high, and B0#, B1#, B2# or B3# = low transition; otherwise t_{AA} is the limiting parameter.

4.t_{CLZ}, t_{BLZ}, t_{OLZ}, t_{CHZ}, t_{BHZ} and t_{OHZ} are specified with C_L = 5pF. Transition is measured ±500mV from steady state.

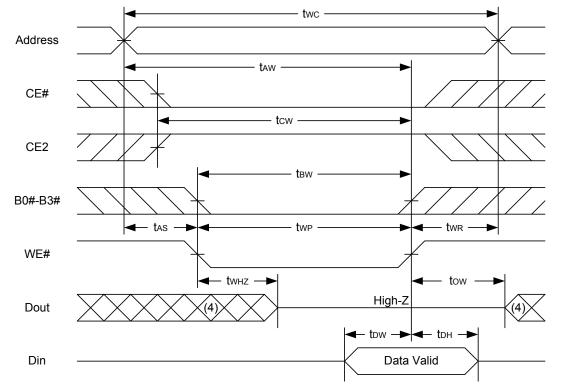
5.At any given temperature and voltage condition, t_{CHZ} is less than t_{CLZ} , t_{BHZ} is less than t_{BLZ} , t_{OHZ} is less than t_{OLZ} .

^{1.}WE# is high for read cycle.

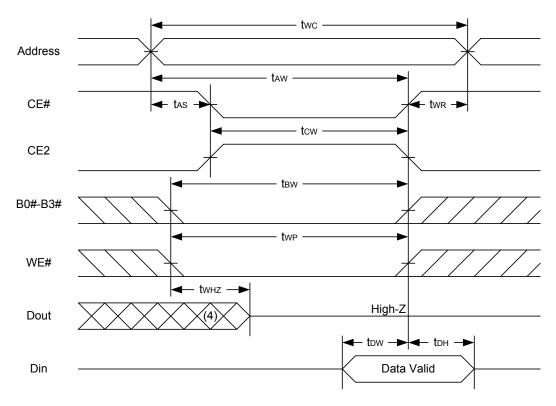


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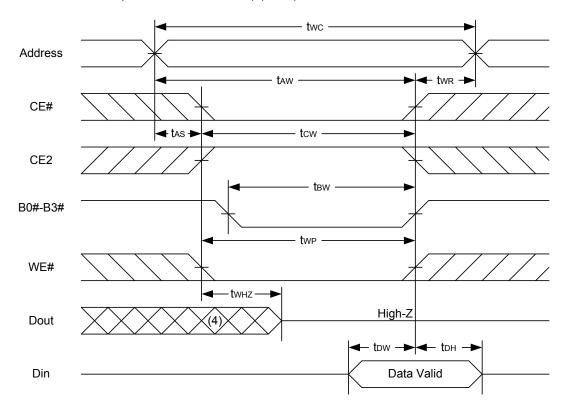
WRITE CYCLE 1 (WE# Controlled) (1,2,4,5)



WRITE CYCLE 2 (CE# and CE2 Controlled) (1,4,5)







WRITE CYCLE 3 (B0# ~ B3# Controlled) (1,4,5)

Notes :

- 1.A write occurs during the overlap of a low CE#, high CE2, low WE#, and B0#, B1#, B2# or B3# = low.
- 2. During a WE# controlled write cycle with OE# low, twp must be greater than twHz + tow to allow the drivers to turn off and data to be placed on the bus.
- 3. During this period, I/O pins are in the output state, and input signals must not be applied. 4. If the CE#, B0# ~ B3# low transition and CE2 high transition occurs simultaneously with or after WE# low transition, the outputs remain in a high impedance state.
- 5.tow and t_{WHZ} are specified with C_L = 5pF. Transition is measured ±500mV from steady state.



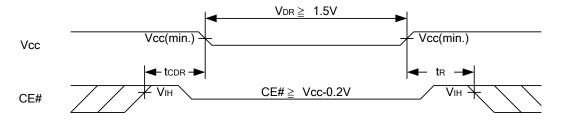
DATA RETENTION CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Vcc for Data Retention	Vdr	$CE\# \ge V_{CC} - 0.2V \text{ or } CE2 \le 0.2V$	1.5	-	3.6	V
Data Retention Current		V_{CC} = 1.5V CE# ≥ V_{CC} - 0.2V or CE2 ≤ 0.2V Other pins at 0.2V or V_{CC} -0.2V	-	4	40	mA
Chip Disable to Data Retention Time	tcdr	See Data Retention Waveforms (below)	0	-	-	ns
Recovery Time	t _R		t RC*	-	-	ns

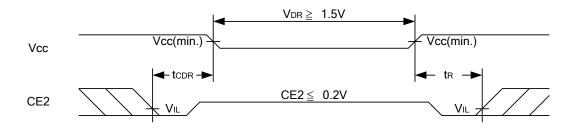
t_{RC*} = Read Cycle Time

DATA RETENTION WAVEFORM

Low Vcc Data Retention Waveform (1) (CE# controlled)



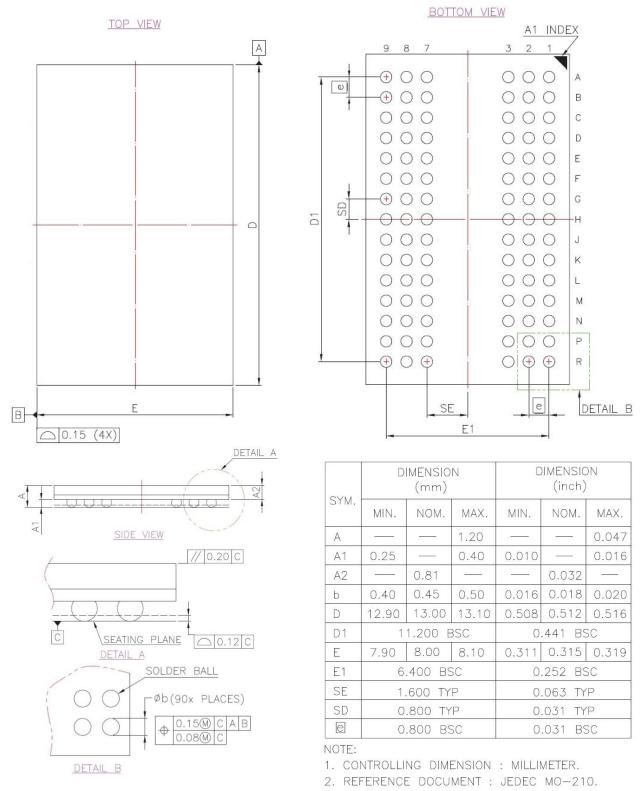
Low Vcc Data Retention Waveform (2) (CE2 controlled)





PACKAGE OUTLINE DIMENSION

90-ball 8mm × 13mm TFBGA Package Outline Dimension





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PART NUMBERING SYSTEM

AS7C	351232	10	В	I	N
SRAM	3=3.3v 51232=512K x 32	10=10 ns	B = TFBGA	l=Industrial (-40° C~+85° C)	Indicates Pb and Halogen Free



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